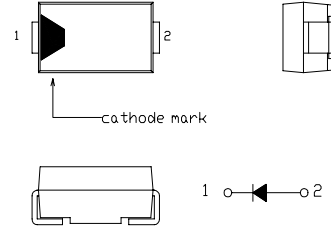


# SBD Type : EC31QS10

## FEATURES

- \* Miniature Size, Surface Mount Device
- \* Low Forward Voltage Drop
- \* Low Power Loss, High Efficiency
- \* High Surge Capability
- \* 30 Volts through 100Volts Types Available
- \* Packaged in 12mm Tape and Reel
- \* Not Rolling During Assembly

## OUTLINE DRAWING



## Maximum Ratings

Approx Net Weight: 0.06g

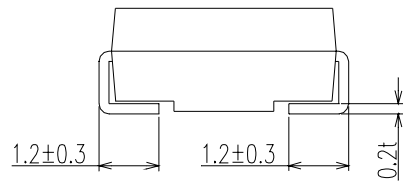
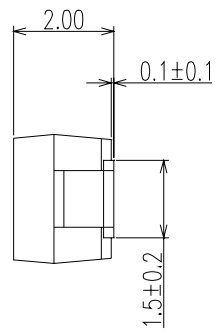
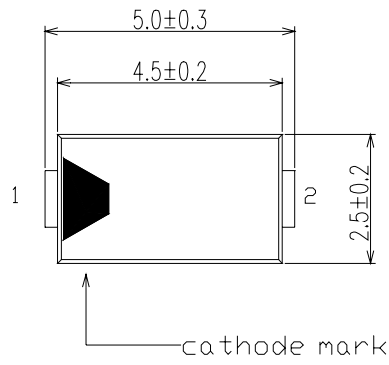
Rating	Symbol	EC31QS10		Unit
Repetitive Peak Reverse Voltage	$V_{RRM}$	100		V
Average Rectified Output Current	$I_O$	1.3	$T_a=26\text{ }^\circ\text{C}$ *1	50Hz Half Sine Wave Resistive Load
		3.0	$T_l=84\text{ }^\circ\text{C}$ $T_l$ :Lead Temperature	
RMS Forward Current	$I_{F(RMS)}$	4.71		A
Surge Forward Current	$I_{FSM}$	60	50Hz Half Sine Wave, 1cycle Non-repetitive	A
Operating Junction Temperature Range	$T_{jw}$	-40 to +150		$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-40 to +150		$^\circ\text{C}$

## Electrical • Thermal Characteristics

Characteristics		Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current		$I_{RM}$	$T_j=25\text{ }^\circ\text{C}$ , $V_{RM}=V_{RRM}$	-	-	2	mA
Peak Forward Voltage		$V_{FM}$	$T_j=25\text{ }^\circ\text{C}$ , $I_{FM}=3.0\text{A}$	-	-	0.85	V
Thermal Resistance	Junction to Ambient	$R_{th(j-a)}$	*1	-	-	108	$^\circ\text{C}/\text{W}$
	Junction to Lead	$R_{th(j-l)}$	-	-	-	23	

\*1 Alumina Substrate Mounted  
Soldering Lands=2x2mm, Both Sides

EC31QS10 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD

